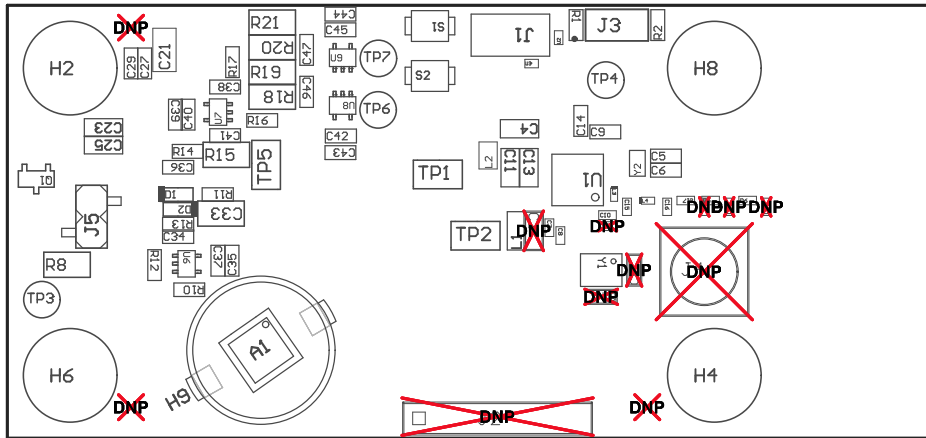


Z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

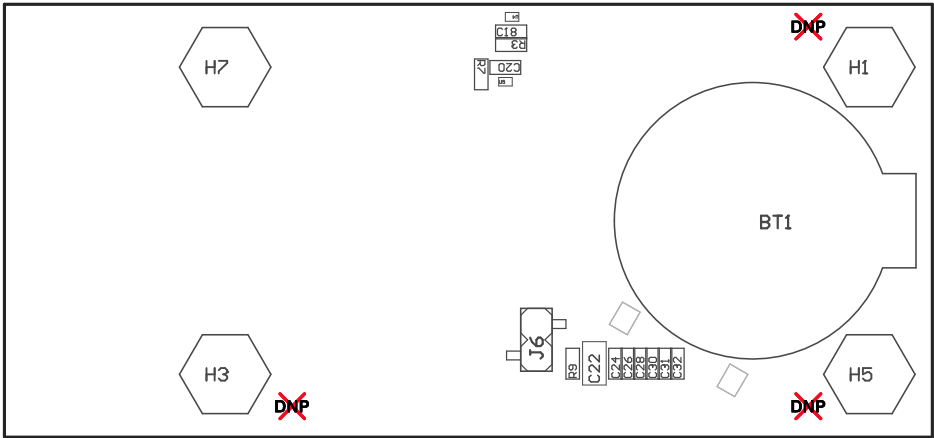
Z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Z24 ■ After verifying lens of A1 is clean and undistorted, snap cover H9 over sensor A1 during final hardware assembly.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: ISE4047	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-00759		
PLOT NAME = Top Assembly Drawing	GENERATED : 2/22/2016	10:26:20 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: ISE4047	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-00759		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/22/2016 10:26:21 AM		TEXAS INSTRUMENTS

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